

PLACEMENT MACHINE AND METHOD FOR BONDING COMPONENTS TO CONTACTS

5

ABSTRACT OF THE DISCLOSURE

10 A placement machine (1) for mounting and bonding components
(2) onto contacts of a laser translucent or laser transparent
substrate (5). The machine (1) has an array of laser beam
outlets (10) associated with an abutment surface for abutting
one surface of the substrate (5). A laser energy generator (11) is
15 operatively coupled to the outlets (10) and there is a pick and
place member (13) for placing one or more of the components
(2) on contacts of the substrate (5). There is a conveyor (6) for
conveying the substrate (5), the conveyor (6) has a section that
is movable towards the outlets (10) and a controller (14) is
20 provided to control movement of the conveyor section relative to
laser beam outlets (10) to thereby provide abutment of the
abutment surface to the one surface of the substrate. The
machine (1) selectively provides laser energy through the outlets
(10) whilst at least one of the components (2) and the substrate
(5) are sandwiched between the outlets (10) and the pick and
25 place member.

Figure 1 accompanies this abstract.